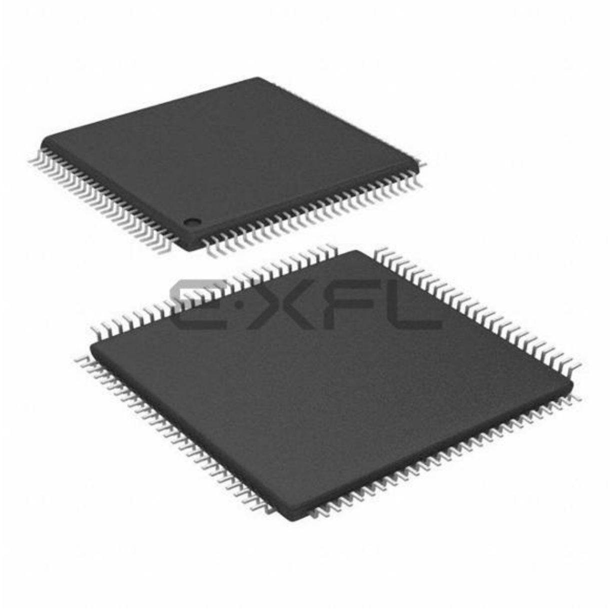
Microchip Technology - PIC32MX130F128L-I/PF Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 48x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx130f128l-i-pf

2.7.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following examples are used to calculate the Primary Oscillator loading capacitor values:

- C_{IN} = PIC32_OSC2_Pin Capacitance = ~4-5 pF
- C_{OUT} = PIC32_OSC1_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended: $C1 = C2 = 15\ pF$

Therefore:

$$C_{LOAD} = \{([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}]\} + \textit{estimated oscillator PCB stray capacitance}$$

$$= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5]\} + 2.5\ pF$$

$$= \{([20][20]) / [40]\} + 2.5$$

$$= 10 + 2.5 = 12.5\ pF$$

Rounded to the nearest standard value or 13 pF in this example for Primary Oscillator crystals “C1” and “C2”.

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

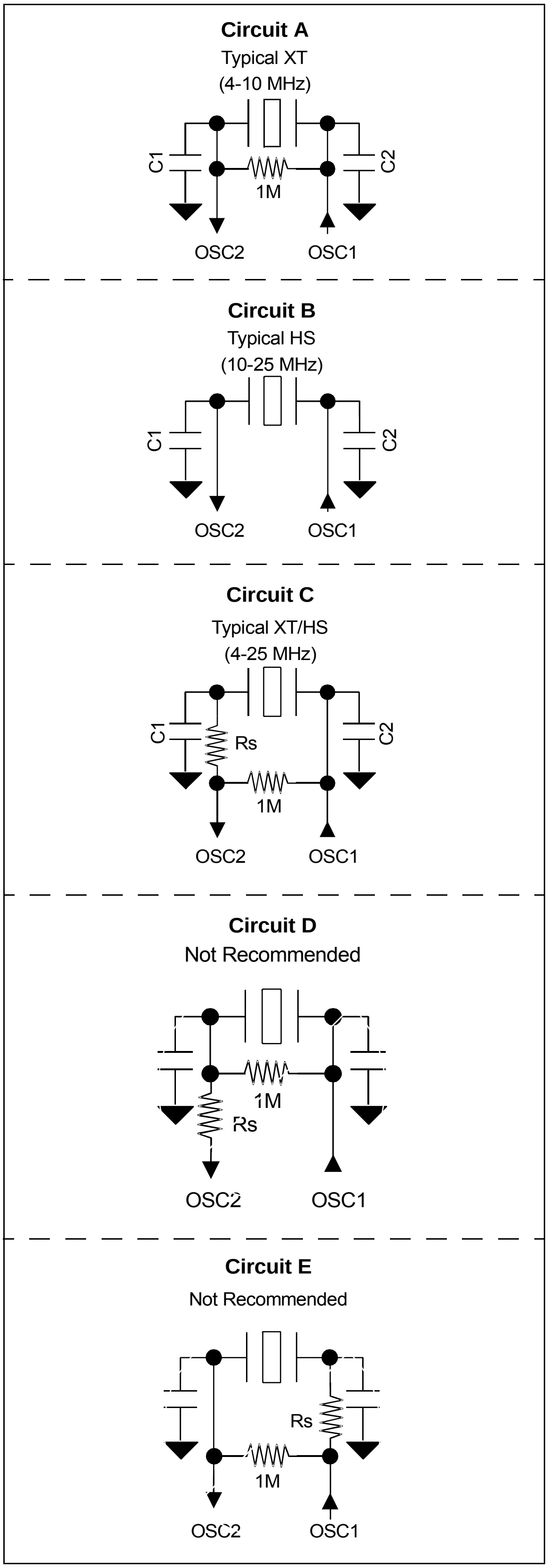
- Select a crystal with a lower “minimum” power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing “ESR” rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

Note: Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit “C” in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~VDD-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with ≤ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.7.1.1 Additional Microchip References

- AN588 *“PICmicro® Microcontroller Oscillator Design Guide”*
- AN826 *“Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices”*
- AN849 *“Basic PICmicro® Oscillator Design”*

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS



Circuit A
Typical XT
(4-10 MHz)

Circuit B
Typical HS
(10-25 MHz)

Circuit C
Typical XT/HS
(4-25 MHz)

Circuit D
Not Recommended

Circuit E
Not Recommended

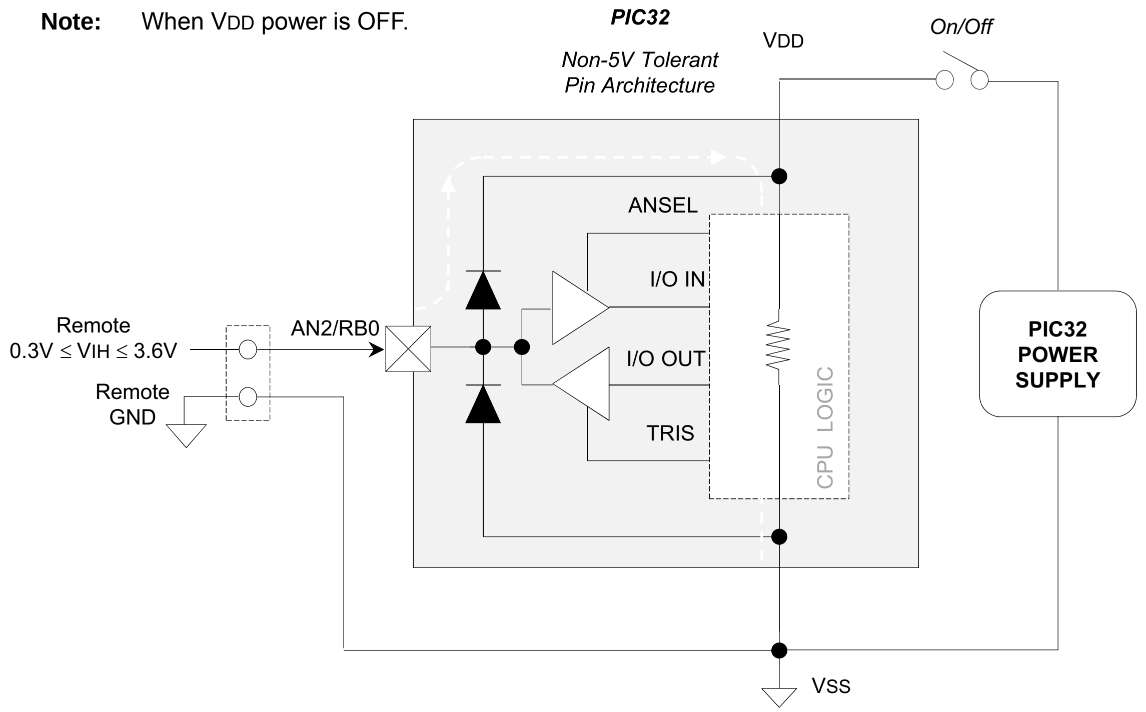
2.9 Considerations When Interfacing to Remotely Powered Circuits

2.9.1 NON-5V TOLERANT INPUT PINS

A quick review of the absolute maximum rating section in **31.0 "40 MHz Electrical Characteristics"** will indicate that the voltage on any non-5v tolerant pin may not exceed AVDD/VDD + 0.3V. Figure 2-5 shows an example of a remote circuit using an independent power source, which is powered while connected to a PIC32 non-5V tolerant circuit that is not powered.

FIGURE 2-5: PIC32 NON-5V TOLERANT CIRCUIT EXAMPLE

Note: When VDD power is OFF.



Coprocessor 0 also contains the logic for identifying and managing exceptions. Exceptions can be caused by a variety of sources, including alignment errors in data, external events or program errors. Table 3-3 lists the exception types in order of priority.

TABLE 3-3: MIPS32® M4K® PROCESSOR CORE EXCEPTION TYPES

Exception	Description
Reset	Assertion $\overline{\text{MCLR}}$ or a Power-on Reset (POR).
DSS	EJTAG debug single step.
DINT	EJTAG debug interrupt. Caused by the assertion of the external *EJ_DINT* input or by setting the EjtagBrk bit in the ECR register.
NMI	Assertion of NMI signal.
Interrupt	Assertion of unmasked hardware or software interrupt signal.
DIB	EJTAG debug hardware instruction break matched.
AdEL	Fetch address alignment error. Fetch reference to protected address.
IBE	Instruction fetch bus error.
DBp	EJTAG breakpoint (execution of `SDBBP` instruction).
Sys	Execution of `SYSCALL` instruction.
Bp	Execution of `BREAK` instruction.
RI	Execution of a reserved instruction.
CpU	Execution of a coprocessor instruction for a coprocessor that is not enabled.
CEU	Execution of a `CorExtend` instruction when `CorExtend` is not enabled.
Ov	Execution of an arithmetic instruction that overflowed.
Tr	Execution of a trap (when trap condition is true).
DDBL/DDBS	EJTAG Data Address Break (address only) or EJTAG data value break on store (address + value).
AdEL	Load address alignment error. Load reference to protected address.
AdES	Store address alignment error. Store to protected address.
DBE	Load or store bus error.
DDBL	EJTAG data hardware breakpoint matched in load data compare.

3.3 Power Management

The MIPS® M4K® processor core offers a number of power management features, including low-power design, active power management and power-down modes of operation. The core is a static design that supports slowing or Halting the clocks, which reduces system power consumption during Idle periods.

3.3.1 INSTRUCTION-CONTROLLED POWER MANAGEMENT

The mechanism for invoking Power-Down mode is through execution of the `WAIT` instruction. For more information on power management, see **Section 27.0 “Power-Saving Features”**.

3.3.2 LOCAL CLOCK GATING

The majority of the power consumed by the PIC32MX1XX/2XX/5XX 64/100-pin family core is in the clock tree and clocking registers. The PIC32MX family uses extensive use of local gated-clocks to reduce this dynamic power consumption.

3.4 EJTAG Debug Support

The MIPS® M4K® processor core provides for an Enhanced JTAG (EJTAG) interface for use in the software debug of application and kernel code. In addition to standard User mode and Kernel modes of operation, the M4K® core provides a Debug mode that is entered after a debug exception (derived from a hardware breakpoint, single-step exception, etc.) is taken and continues until a Debug Exception Return (`DERET`) instruction is executed. During this time, the processor executes the debug exception handler routine.

The EJTAG interface operates through the Test Access Port (TAP), a serial communication port used for transferring test data in and out of the core. In addition to the standard JTAG instructions, special instructions defined in the EJTAG specification define which registers are selected and how they are used.

REGISTER 5-1: INTCON: INTERRUPT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
	—	—	—	MVEC	—	TPC<2:0>		
7:0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-13 **Unimplemented:** Read as ‘0’

bit 12 **MVEC:** Multi Vector Configuration bit

1 = Interrupt controller configured for multi vectored mode
0 = Interrupt controller configured for single vectored mode

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **TPC<2:0>:** Interrupt Proximity Timer Control bits

111 = Interrupts of group priority 7 or lower start the Interrupt Proximity timer
110 = Interrupts of group priority 6 or lower start the Interrupt Proximity timer
101 = Interrupts of group priority 5 or lower start the Interrupt Proximity timer
100 = Interrupts of group priority 4 or lower start the Interrupt Proximity timer
011 = Interrupts of group priority 3 or lower start the Interrupt Proximity timer
010 = Interrupts of group priority 2 or lower start the Interrupt Proximity timer
001 = Interrupts of group priority 1 start the Interrupt Proximity timer
000 = Disables Interrupt Proximity timer

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4 **INT4EP:** External Interrupt 4 Edge Polarity Control bit

1 = Rising edge
0 = Falling edge

bit 3 **INT3EP:** External Interrupt 3 Edge Polarity Control bit

1 = Rising edge
0 = Falling edge

bit 2 **INT2EP:** External Interrupt 2 Edge Polarity Control bit

1 = Rising edge
0 = Falling edge

bit 1 **INT1EP:** External Interrupt 1 Edge Polarity Control bit

1 = Rising edge
0 = Falling edge

bit 0 **INT0EP:** External Interrupt 0 Edge Polarity Control bit

1 = Rising edge
0 = Falling edge

NOTES:

TABLE 10-1: USB REGISTER MAP (CONTINUED)

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits 31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
5280	U1FRML(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	FRML<7:0>								0000
5290	U1FRMH(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	FRMH<2:0>			0000
52A0	U1TOK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	PID<3:0>				EP<3:0>				0000
52B0	U1SOF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CNT<7:0>								0000
52C0	U1BDTP2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BDTPTRH<23:16>								0000
52D0	U1BDTP3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	BDTPTRU<31:24>								0000
52E0	U1CNFG1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	UTEYE	—	—	USBSIDL	LSDEV	—	—	UASUSPND	0000
5300	U1EP0	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	LSPD	RETRYDIS	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5310	U1EP1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5320	U1EP2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5330	U1EP3	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5340	U1EP4	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5350	U1EP5	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5360	U1EP6	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5370	U1EP7	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5380	U1EP8	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: With the exception of those noted, all registers in this table (except as noted) have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC respectively. See **Section 11.2 “CLR, SET, and INV Registers”** for more information.

2: This register does not have associated SET and INV registers.

3: This register does not have associated CLR, SET and INV registers.

4: Reset value for this bit is undefined.

TABLE 10-1: USB REGISTER MAP (CONTINUED)

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5390	U1EP9	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53A0	U1EP10	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53B0	U1EP11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53C0	U1EP12	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53D0	U1EP13	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53E0	U1EP14	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53F0	U1EP15	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: With the exception of those noted, all registers in this table (except as noted) have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC respectively. See **Section 11.2 “CLR, SET, and INV Registers”** for more information.

2: This register does not have associated SET and INV registers.

3: This register does not have associated CLR, SET and INV registers.

4: Reset value for this bit is undefined.

REGISTER 10-7: U1IE: USB INTERRUPT ENABLE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	STALLIE	ATTACHIE	RESUMEIE	IDLEIE	TRNIE	SOFIE	UERRIE(1)	URSTIE(2) DETACHIE(3)

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as ‘0’

bit 7 **STALLIE:** STALL Handshake Interrupt Enable bit
1 = STALL interrupt enabled
0 = STALL interrupt disabled

bit 6 **ATTACHIE:** ATTACH Interrupt Enable bit
1 = ATTACH interrupt enabled
0 = ATTACH interrupt disabled

bit 5 **RESUMEIE:** RESUME Interrupt Enable bit
1 = RESUME interrupt enabled
0 = RESUME interrupt disabled

bit 4 **IDLEIE:** Idle Detect Interrupt Enable bit
1 = Idle interrupt enabled
0 = Idle interrupt disabled

bit 3 **TRNIE:** Token Processing Complete Interrupt Enable bit
1 = TRNIF interrupt enabled
0 = TRNIF interrupt disabled

bit 2 **SOFIE:** SOF Token Interrupt Enable bit
1 = SOFIF interrupt enabled
0 = SOFIF interrupt disabled

bit 1 **UERRIE:** USB Error Interrupt Enable bit(1)
1 = USB Error interrupt enabled
0 = USB Error interrupt disabled

bit 0 **URSTIE:** USB Reset Interrupt Enable bit(2)
1 = URSTIF interrupt enabled
0 = URSTIF interrupt disabled

DETACHIE: USB Detach Interrupt Enable bit(3)
1 = DATTCHIF interrupt enabled
0 = DATTCHIF interrupt disabled

Note 1: For an interrupt to propagate USBIF, the UERRIE bit (U1IE<1>) must be set.
2: Device mode.
3: Host mode.

13.0 TIMER2/3, TIMER4/5

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 14. “Timers”** (DS60001105) of the *“PIC32 Family Reference Manual”*, which is available from the Microchip web site (www.microchip.com/PIC32).

This family of PIC32 devices features four synchronous 16-bit timers (default) that can operate as a free-running interval timer for various timing applications and counting external events. The following modes are supported:

- Synchronous internal 16-bit timer
- Synchronous internal 16-bit gated timer
- Synchronous external 16-bit timer

Two 32-bit synchronous timers are available by combining Timer2 with Timer3 and Timer4 with Timer5. The 32-bit timers can operate in three modes:

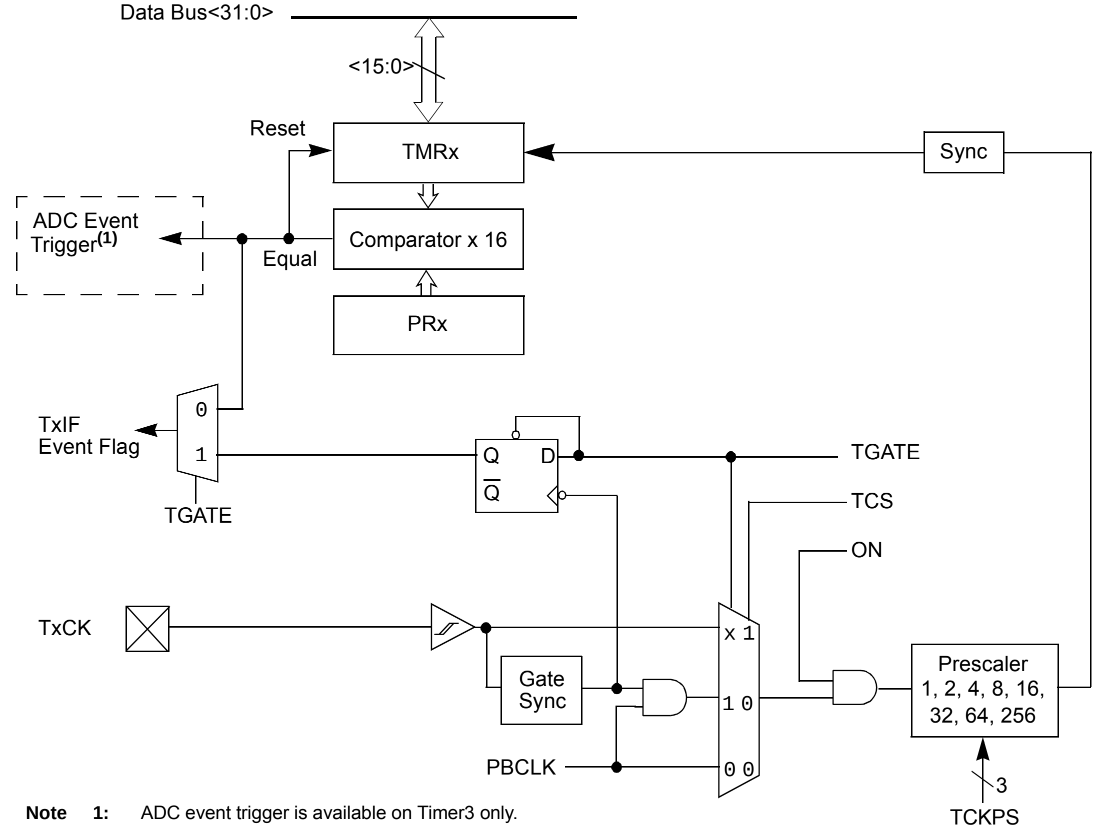
- Synchronous internal 32-bit timer
- Synchronous internal 32-bit gated timer
- Synchronous external 32-bit timer

Note: In this chapter, references to registers, TxCON, TMRx and PRx, use ‘x’ to represent Timer2 through 5 in 16-bit modes. In 32-bit modes, ‘x’ represents Timer2 or 4; ‘y’ represents Timer3 or 5.

13.1 Additional Supported Features

- Selectable clock prescaler
- Timers operational during CPU idle
- Time base for Input Capture and Output Compare modules (Timer2 and Timer3 only)
- ADC event trigger (Timer3 in 16-bit mode, Timer2/3 in 32-bit mode)
- Fast bit manipulation using CLR, SET and INV registers

FIGURE 13-1: TIMER2, 3, 4, 5 BLOCK DIAGRAM (16-BIT)



Note 1: ADC event trigger is available on Timer3 only.

REGISTER 16-1: OCxCON: OUTPUT COMPARE ‘x’ CONTROL REGISTER (‘x’ = 1 THROUGH 5)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON[1]	—	SIDL	—	—	—	—	—
7:0	U-0	U-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	OC32	OCFLT[2]	OCTSEL	OCM<2:0>		

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’

-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘0’

bit 15 **ON:** Output Compare Peripheral On bit[1]

1 = Output Compare peripheral is enabled
0 = Output Compare peripheral is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **SIDL:** Stop in Idle Mode bit

1 = Discontinue operation when CPU enters Idle mode
0 = Continue operation in Idle mode

bit 12-6 **Unimplemented:** Read as ‘0’

bit 5 **OC32:** 32-bit Compare Mode bit

1 = OCxR<31:0> and/or OCxRS<31:0> are used for comparisons to the 32-bit timer source
0 = OCxR<15:0> and OCxRS<15:0> are used for comparisons to the 16-bit timer source

bit 4 **OCFLT:** PWM Fault Condition Status bit[2]

1 = PWM Fault condition has occurred (cleared in HW only)
0 = No PWM Fault condition has occurred

bit 3 **OCTSEL:** Output Compare Timer Select bit

1 = Timer3 is the clock source for this Output Compare module
0 = Timer2 is the clock source for this Output Compare module

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits

111 = PWM mode on OCx; Fault pin enabled
110 = PWM mode on OCx; Fault pin disabled
101 = Initialize OCx pin low; generate continuous output pulses on OCx pin
100 = Initialize OCx pin low; generate single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initialize OCx pin high; compare event forces OCx pin low
001 = Initialize OCx pin low; compare event forces OCx pin high
000 = Output compare peripheral is disabled but continues to draw current

Note 1: When using 1:1 PBCLK divisor, the user software should not read/write the peripheral’s SFRs in the SYSCLK cycle immediately following the instruction that clears the module’s ON bit.

2: This bit is only used when OCM<2:0> = ‘111’. It is read as ‘0’ in all other modes.

26.1 Control Registers

TABLE 26-1: CTMU REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
A200	CTMUCON	31:16	EDG1MOD	EDG1POL	EDG1SEL<3:0>				EDG2STAT	EDG1STAT	EDG2MOD	EDG2POL	EDG2SEL<3:0>				—	—	0000
		15:0	ON	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG	ITRIM<5:0>						IRNG<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 “CLR, SET, and INV Registers”** for more information.

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	EDG1MOD	EDG1POL	EDG1SEL<3:0>				EDG2STAT	EDG1STAT
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
	EDG2MOD	EDG2POL	EDG2SEL<3:0>				—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ON	—	CTMUSIDL	TGEN[(1)]	EDGEN	EDGSEQEN	IDISSEN[(2)]	CTTRIG
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ITRIM<5:0>						IRNG<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31 **EDG1MOD:** Edge 1 Edge Sampling Select bit

`1` = Input is edge-sensitive
`0` = Input is level-sensitive

bit 30 **EDG1POL:** Edge 1 Polarity Select bit

`1` = Edge 1 programmed for a positive edge response
`0` = Edge 1 programmed for a negative edge response

bit 29-26 **EDG1SEL<3:0>:** Edge 1 Source Select bits

`1111` = IC4 Capture Event is selected
`1110` = C2OUT pin is selected
`1101` = C1OUT pin is selected
`1100` = IC3 Capture Event is selected
`1011` = IC2 Capture Event is selected
`1010` = IC1 Capture Event is selected
`1001` = CTED8 pin is selected
`1000` = CTED7 pin is selected
`0111` = CTED6 pin is selected
`0110` = CTED5 pin is selected
`0101` = CTED4 pin is selected
`0100` = CTED3 pin is selected
`0011` = CTED1 pin is selected
`0010` = CTED2 pin is selected
`0001` = OC1 Compare Event is selected
`0000` = Timer1 Event is selected

bit 25 **EDG2STAT:** Edge 2 Status bit

Indicates the status of Edge 2 and can be written to control edge source

`1` = Edge 2 has occurred
`0` = Edge 2 has not occurred

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to ‘`1110`’ to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘`1`’, performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 31-41) in **Section 31.0 “40 MHz Electrical Characteristics”** for current values.

4: This bit setting is not available for the CTMU temperature diode.

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge 1 Status bit

Indicates the status of Edge 1 and can be written to control edge source

`1` = Edge 1 has occurred
`0` = Edge 1 has not occurred

bit 23 **EDG2MOD:** Edge 2 Edge Sampling Select bit

`1` = Input is edge-sensitive
`0` = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit

`1` = Edge 2 programmed for a positive edge response
`0` = Edge 2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits

`1111` = IC4 Capture Event is selected
`1110` = C2OUT pin is selected
`1101` = C1OUT pin is selected
`1100` = PBCLK clock is selected
`1011` = IC3 Capture Event is selected
`1010` = IC2 Capture Event is selected
`1001` = IC1 Capture Event is selected
`1000` = CTED13 pin is selected
`0111` = CTED12 pin is selected
`0110` = CTED11 pin is selected
`0101` = CTED10 pin is selected
`0100` = CTED9 pin is selected
`0011` = CTED1 pin is selected
`0010` = CTED2 pin is selected
`0001` = OC1 Compare Event is selected
`0000` = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as ‘`0`’

bit 15 **ON:** ON Enable bit

`1` = Module is enabled
`0` = Module is disabled

bit 14 **Unimplemented:** Read as ‘`0`’

bit 13 **CTMUSIDL:** Stop in Idle Mode bit

`1` = Discontinue module operation when device enters Idle mode
`0` = Continue module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit[(1)]

`1` = Enables edge delay generation
`0` = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit

`1` = Edges are not blocked
`0` = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to ‘`1110`’ to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘`1`’, performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 31-41) in **Section 31.0 “40 MHz Electrical Characteristics”** for current values.

4: This bit setting is not available for the CTMU temperature diode.

REGISTER 28-2: DEVCFG1: DEVICE CONFIGURATION WORD 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	R/P	R/P
	—	—	—	—	—	—	FWDTWINSZ<1:0>	
23:16	R/P	R/P	r-1	R/P	R/P	R/P	R/P	R/P
	FWDTEN	WINDIS	—	WDTPS<4:0>				
15:8	R/P	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>	
7:0	R/P	r-1	R/P	r-1	r-1	R/P	R/P	R/P
	IESO	—	FSOSCEN	—	—	FNOSC<2:0>		

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-26 **Reserved:** Write ‘`1`’

bit 25-24 **FWDTWINSZ:** Watchdog Timer Window Size bits

`11` = Window size is 25%
`10` = Window size is 37.5%
`01` = Window size is 50%
`00` = Window size is 75%

bit 23 **FWDTEN:** Watchdog Timer Enable bit

`1` = Watchdog Timer is enabled and cannot be disabled by software
`0` = Watchdog Timer is not enabled; it can be enabled in software

bit 22 **WINDIS:** Watchdog Timer Window Enable bit

`1` = Watchdog Timer is in non-Window mode
`0` = Watchdog Timer is in Window mode

bit 21 **Reserved:** Write ‘`1`’

bit 20-16 **WDTPS<4:0>:** Watchdog Timer Postscale Select bits

`10100` = 1:1048576
`10011` = 1:524288
`10010` = 1:262144
`10001` = 1:131072
`10000` = 1:65536
`01111` = 1:32768
`01110` = 1:16384
`01101` = 1:8192
`01100` = 1:4096
`01011` = 1:2048
`01010` = 1:1024
`01001` = 1:512
`01000` = 1:256
`00111` = 1:128
`00110` = 1:64
`00101` = 1:32
`00100` = 1:16
`00011` = 1:8
`00010` = 1:4
`00001` = 1:2
`00000` = 1:1
All other combinations not shown result in operation = `10100`

Note 1: Do not disable the POSC (POSCMOD = `11`) when using this oscillator source.

30.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

30.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

30.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

30.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

31.1 DC Characteristics

TABLE 31-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)[1]	Temp. Range (in °C)	Max. Frequency
			PIC32MX1XX/2XX/5XX 64/100-pin Family
DC5	VBOR-3.6V	-40°C to +105°C	40 MHz

Note 1: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 31-10 for BOR values.

TABLE 31-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typical	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
V-temp Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+105	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – S IOH) I/O Pin Power Dissipation: I/O = S (({VDD – VOH} x IOH) + S (VOL x IOL))	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 31-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typical	Max.	Unit	Notes
Package Thermal Resistance, 64-pin QFN	θJA	28	—	°C/W	**1**
Package Thermal Resistance, 64-pin TQFP, 10 mm x 10 mm	θJA	55	—	°C/W	**1**
Package Thermal Resistance, 100-pin TQFP, 12 mm x 12 mm	θJA	52	—	°C/W	**1**
Package Thermal Resistance, 100-pin TQFP, 14 mm x 14 mm	θJA	50	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 31-14: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
D312	TSET	Internal 4-bit DAC Comparator Reference Settling time.	—	—	10	µs	See **Note 1**
D313	DACREFH	CVREF Input Voltage Reference Range	AVSS	—	AVDD	V	CVRSRC with CVRSS = `0`
			VREF-	—	VREF+	V	CVRSRC with CVRSS = `1`
D314	DVREF	CVREF Programmable Output Range	0	—	0.625 x DACREFH	V	0 to 0.625 DACREFH with DACREFH/24 step size
			0.25 x DACREFH	—	0.719 x DACREFH	V	0.25 x DACREFH to 0.719 DACREFH with DACREFH/32 step size
D315	DACRES	Resolution	—	—	DACREFH/24		CVRCON<CVRR> = `1`
			—	—	DACREFH/32		CVRCON<CVRR> = `0`
D316	DACACC	Absolute Accuracy(2)	—	—	1/4	LSB	DACREFH/24, CVRCON<CVRR> = `1`
			—	—	1/2	LSB	DACREFH/32, CVRCON<CVRR> = `0`

Note 1: Settling time was measured while CVRR = 1 and CVR<3:0> transitions from '`0000`' to '`1111`'. This parameter is characterized, but is not tested in manufacturing.

2: These parameters are characterized but not tested.

TABLE 31-15: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D321	CEFC	External Filter Capacitor Value	8	10	—	µF	Capacitor must be low series resistance (≤ 3 ohm). Typical voltage on the VCAP pin is 1.8V.

TABLE 31-41: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions (see Note 3):2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
CTMU CURRENT SOURCE							
CTMUI1	IOUT1	Base Range[1]	—	0.55	—	µA	CTMUCON<9:8> = `01`
CTMUI2	IOUT2	10x Range[1]	—	5.5	—	µA	CTMUCON<9:8> = `10`
CTMUI3	IOUT3	100x Range[1]	—	55	—	µA	CTMUCON<9:8> = `11`
CTMUI4	IOUT4	1000x Range[1]	—	550	—	µA	CTMUCON<9:8> = `00`
CTMUFV1	VF	Temperature Diode Forward Voltage[1,2]	—	0.598	—	V	TA = +25ºC, CTMUCON<9:8> = `01`
			—	0.658	—	V	TA = +25ºC, CTMUCON<9:8> = `10`
			—	0.721	—	V	TA = +25ºC, CTMUCON<9:8> = `11`
CTMUFV2	VFVR	Temperature Diode Rate of Change[1,2]	—	-1.92	—	mV/ºC	CTMUCON<9:8> = `01`
			—	-1.74	—	mV/ºC	CTMUCON<9:8> = `10`
			—	-1.56	—	mV/ºC	CTMUCON<9:8> = `11`

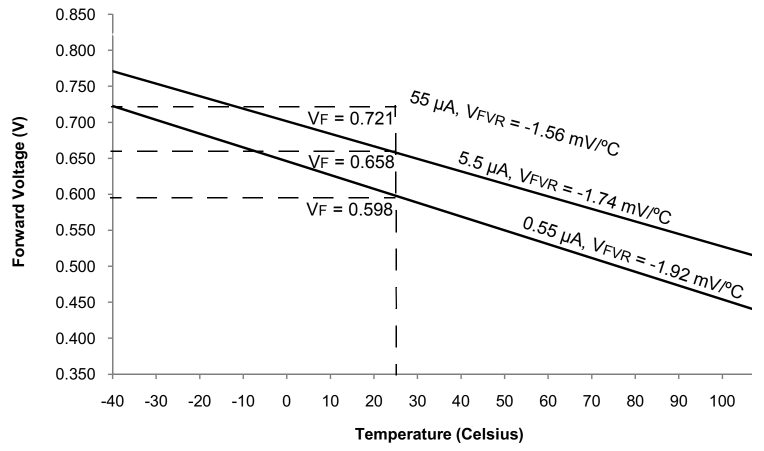
Note 1: Nominal value at center point of current trim range (CTMUCON<15:10> = `000000`).

2: Parameters are characterized but not tested in manufacturing. Measurements taken with the following conditions:

- VREF+ = AVDD = 3.3V
- ADC module configured for conversion speed of 500 ksps
- All PMD bits are cleared (PMDx = `0`)
- Executing a `while(1)` statement
- Device operating from the FRC with no PLL

3: The CTMU module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

FIGURE 33-5: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE

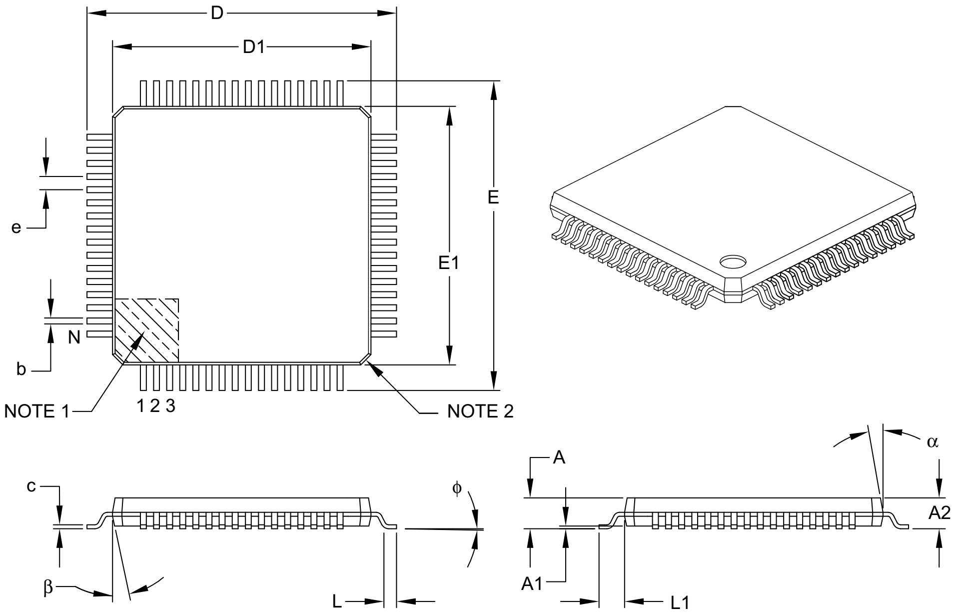


34.2 Package Details

The following sections give the technical details of the packages.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	64		
Lead Pitch	e	0.50 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B